

101155C

ID353.125-168.75-1.024W- 353.125 MHz Dispersive Delay Line 168.8 MHz Bandwidth

Specifications

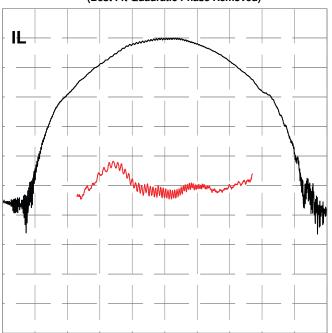
Parameter	Symbol	Min	Typical	Max	Unit
Center Frequency	F ₀		353.125		MHz
Bandwidth	В		168.75		MHz
Dispersion	Т		1.024		µsec
Delay	T ₀	2.12	2.133	2.14	µsec
Insertion Loss	IL		26.6	28	dB
Slope	S ₀	-0.0063	-0.0062	-0.0061	µs/MHz
Pulse Width at -3 dB			0.0075	0.0076	µsec
Sidelobes for $ t - T_0 < T$			-32	-23	dB
Time Spurious for $ t - T_0 > T$			-74	-70	dB
Substrate Material	128YX-LN				

Notes

- 1. Center Frequency (F_0) and Bandwidth (B) are defined, not measured. Dispersion (T) is defined as $|B^*S_0|$.
- 2. Insertion Loss is the minimum loss for $|f-F_0| < .5B$
- 3. Delay and Slope determined by best fit quadratic pulse in $|f F_0| < .5B$.
- 4. Specifications are at 22 °C only. Unit will operate undamaged from -54 °C to 125 °C with shifts $dF_0 = -x * F_0$, $dT_0 = x * (T_0 + S_0 * F_0)$, $dS_0 = x * 2 * S_0$, where x = 75E-6 * (temperature 22 °C)

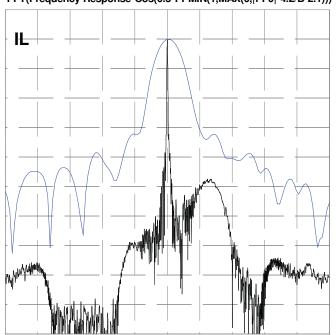
Typical Performance

Frequency Response (Best Fit Quadratic Phase Removed)



10 dB/div, 10 deg/div, 25.000 MHz/div

Compressed Pulse Response FFT(Frequency Response*Cos(0.5*PI*MIN(1,MAX(0,|f-F0|*4.2/B-2.1)))^2)



10 dB/div, 0.400 us/div, 0.013 us/div



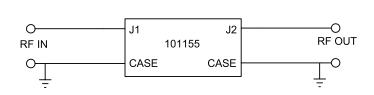
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Package Outline

1.100 .908 .012 R.05 R.07 MAX Microsemi. J2 6Y858 1.100 .900 700 101155 DATE CODE .500 SERIAL NO. .108 - .050 .300 1.85

Matching





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